PhoPack™ 2003

PHOTONIC DEVICES & SYSTEMS PACKAGING

August 10-12, 2003

San Francisco, CA USA

This jointly sponsored symposium brings attendees into the forefront of photonic device packaging technology. The technical sessions explore major packaging technology areas and provide a state-of-the-art technical introduction. Technical presenters are leaders in their technology areas. Attendees have free access to the exhibits and programs of **WESCON**, the IEEE's major west coast exposition, which runs concurrently at San Francisco's Moscone Convention Center.

Professional Development Courses – Sunday, August 10:

- **Photonics Packaging: Critical Component Assembly and Test Processes**
- **How to Make a Photonic Device Into a Product: Role of Accelerated Life Testing**
- **Modeling and Simulations for Photonics Packaging**

PhoPack Symposium – Monday and Tuesday, August 11-12:

Keynote: **A Novel Way of Actively Aligning the Optics as Part of the Device**

Invited: **Wafer Level Packaging of MOEMS: Manufacturability Challenges In Optical Cross Connect**
Thermal Issues in Active and Passive Optoelectronic Devices and Integrated Circuits
Optical Alignment
The Photonics of Pulse Oximetry
Monolithic Integration Technology
New Hybrid Assembly Technology

Fluxless Wafer-Level Packaging of MEMS and Photonic Integration
Design Requirements for Passive Attachment of a Lensed Cap on a TO header for Laser Coaxial Packaging
Reducing Packaging Costs Through Automation of Fiber Pigtails
Optical Modeling of Channelized MEMS Equalization Filter/Blocker
Optical Nanocomposite Materials for Photonic Packaging
MEMS Reliability Testing in Optical Switching Applications
Overview of Optical Medical Sensors
Design of a Uniform Scattering Element for Biomedical Applications
Adhesives and Adhesion Reliability
New Evanescent Coupling Technology with Flip-chip Passive Assembly
New "Optical Processor" Amplifier/Repeater Scheme for Gigabit Optics
Resource-Saving Optoelectronic Micro System Integration Process-Photolithographic Packaging with Selectively Occupied Repeated Transfer (PL-Pack with SORT)
The Effects of CTE Mismatch on Optical Performance of Packaged Planar Lightwave Circuit

Plan to attend!

Additional information and registration forms may be found at www.cpmt.org/phopack/

More information: email **phopack@ieee.org**